Electronic Patent Application Fee Transmittal							
Application Number:	10553470						
Filing Date:	19-May-2006						
Title of Invention:	Monitoring the reduction in thickness as material is removed from a wafer composite and test structure for monitoring removal of material						
First Named Inventor/Applicant Name:	Raif Lerner						
Filer:	Dwight M. Benner/Patricia Hodge						
Attorney Docket Number:	60291.000041						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 2 months with \$0 paid		1252	1	460	460		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			460